



YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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企业微信二维码



企业QQ二维码

Features

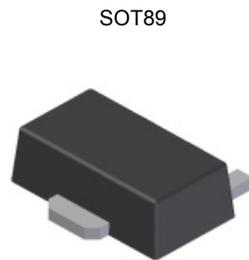
- $BV_{CEO} > -80V$
- $I_C = -1A$ High Continuous Current
- Low saturation voltage $V_{CE(sat)} < -250mV @ -150mA$
- Complementary type NK-BSR43

Application

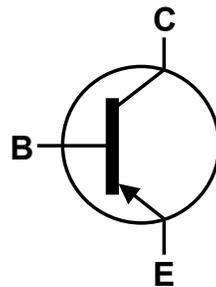
- Load management functions
- Solenoid, relay and actuator drivers
- DC – DC modules

Mechanical Data

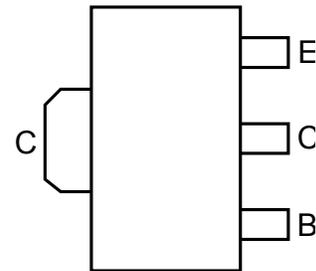
- Case: SOT89
- Case Material: Molded Plastic, "Green" Molding Compound
UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish, Solderable per MIL-STD-202,
Method 208 
- Weight: 0.052 grams (Approximate)



Top View



Device Symbol



Top View
Pin-Out

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-90	V
Collector-Emitter Voltage	V _{CEO}	-80	V
Emitter-Base Voltage	V _{EBO}	-5	V
Continuous Collector Current	I _C	-1	A
Peak Pulse Current	I _{CM}	-2	A
Peak Base Current	I _{BM}	-200	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

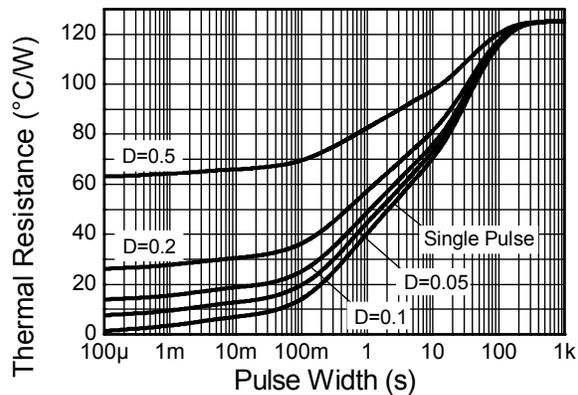
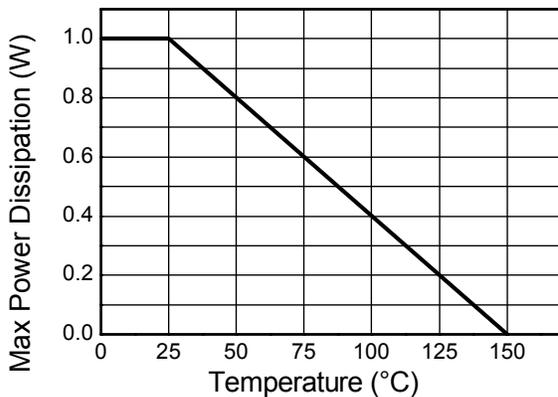
Characteristic	Symbol	Value	Unit
Power Dissipation	P _D	(Note 6)	1
		(Note 7)	1.5
		(Note 8)	2.1
Thermal Resistance, Junction to Ambient Air	R _{θJA}	(Note 6)	125
		(Note 7)	83
		(Note 8)	60
Thermal Resistance, Junction to Lead	R _{θJL}	13	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

ESD Ratings (Note 10)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

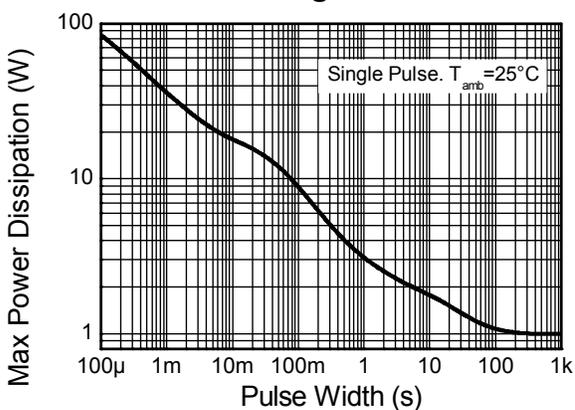
- Notes:
6. For a device mounted with the exposed collector pad on 15mm x 15mm 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
 7. Same as note (6), except the device is mounted on 25mm x 25mm 1oz copper.
 8. Same as note (6), except the device is mounted on 50mm x 50mm 1oz copper.
 9. Thermal resistance from junction to solder-point (on the exposed collector pad).
 10. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information

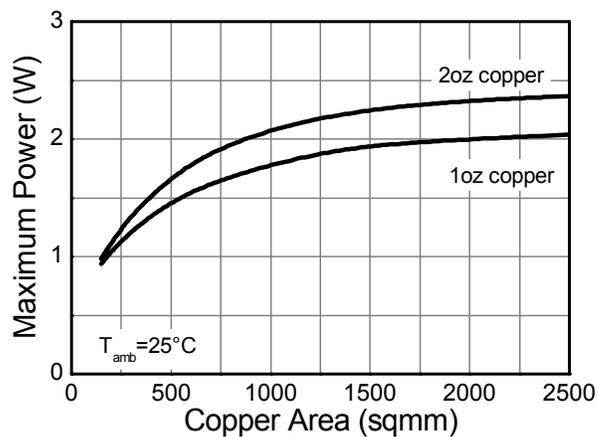
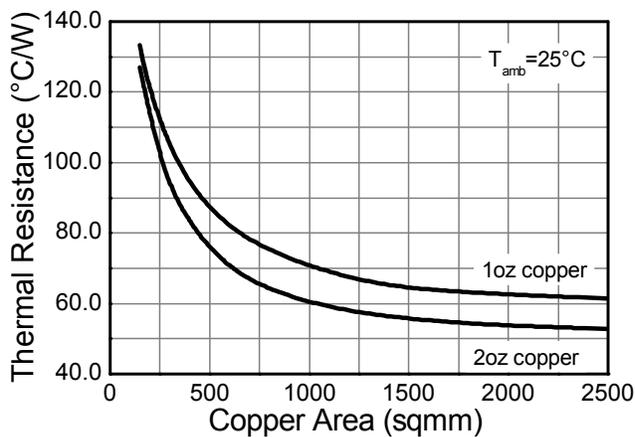


Transient Thermal Impedance

Derating Curve



Pulse Power Dissipation

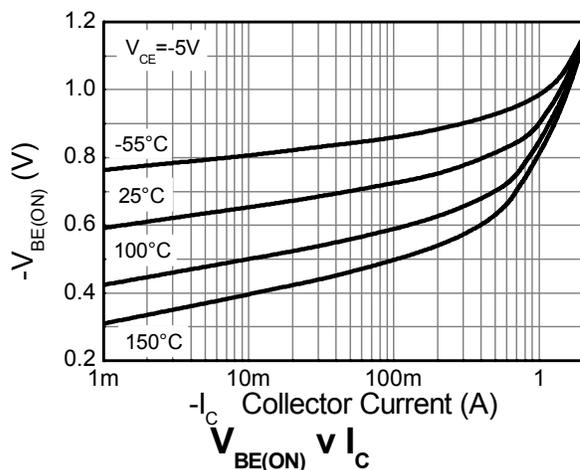
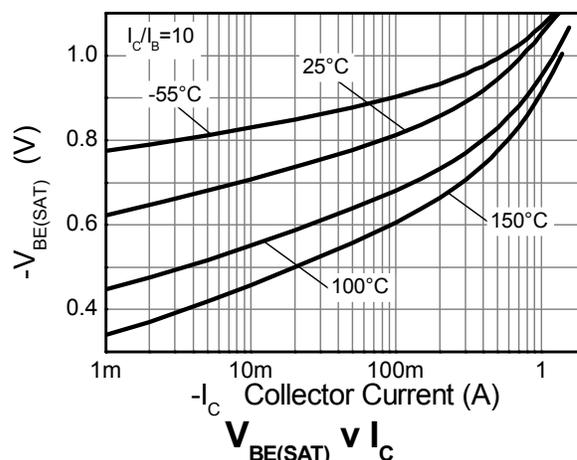
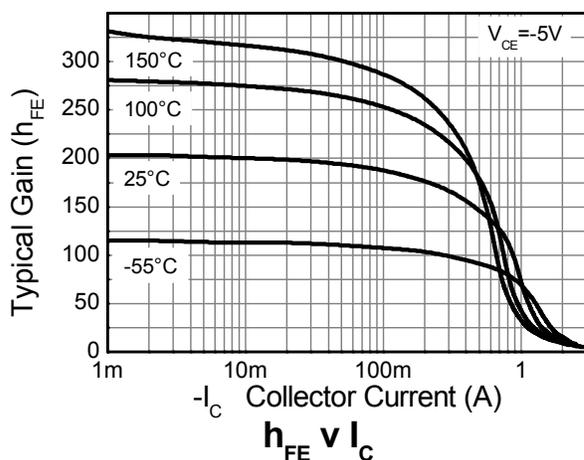
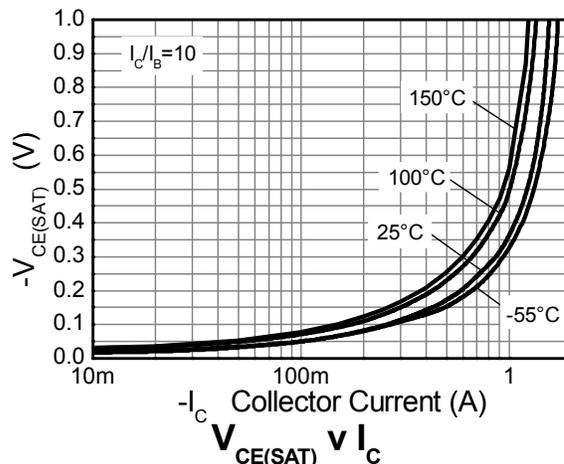
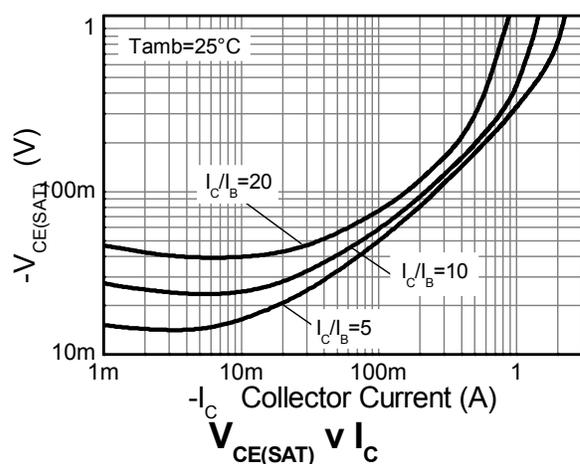


Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

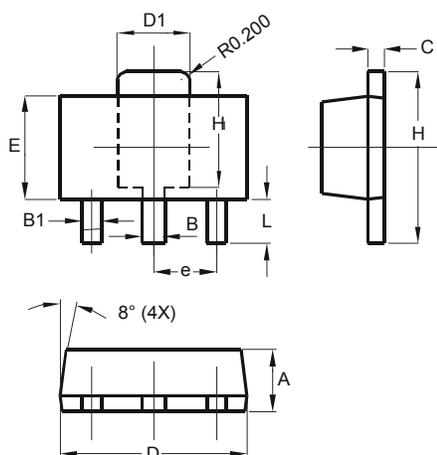
Characteristic	Symbol	Min	Typ.	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV_{CBO}	-90	–	–	V	$I_C = -100\mu\text{A}$
Collector-Emitter Breakdown Voltage (Note 11)	BV_{CEO}	-80	–	–	V	$I_C = -10\text{mA}$
Emitter-Base Breakdown Voltage	BV_{EBO}	-5	–	–	V	$I_E = -100\mu\text{A}$
Collector Cutoff Current	I_{CBO}	–	–	-100 -50	nA μA	$V_{CB} = -60\text{V}$ $V_{CB} = -60\text{V}, T_J = +150^\circ\text{C}$
DC current transfer Static ratio (Note 11)	h_{FE}	30 100 50	– – –	– 300 –	–	$I_C = -100\mu\text{A}, V_{CE} = -5\text{V}$ $I_C = -100\text{mA}, V_{CE} = -5\text{V}$ $I_C = -500\text{mA}, V_{CE} = -5\text{V}$
Collector-Emitter Saturation Voltage (Note 11)	$V_{CE(sat)}$	– –	– –	-0.25 -0.5	V	$I_C = -150\text{mA}, I_B = -15\text{mA}$ $I_C = -500\text{mA}, I_B = -50\text{mA}$
Base-Emitter Saturation Voltage (Note 11)	$V_{BE(sat)}$	–	–	-1.0 -1.2	V	$I_C = -150\text{mA}, I_B = -15\text{mA}$ $I_C = -500\text{mA}, I_B = -50\text{mA}$
Transitional Frequency	f_T	100	–	–	MHz	$I_C = -50\text{mA}, V_{CE} = -10\text{V}$ $f = 35\text{MHz}$
Output capacitance	C_{obo}	–	–	20	pF	$V_{CB} = -10\text{V}, f = 1\text{MHz}$
Input Capacitance	C_{ibo}	–	–	120	pF	$V_{CB} = -0.5\text{V}, f = 1\text{MHz}$
Turn-On Time	T_{on}	–	–	500	ns	$V_{CC} = -20\text{V}, I_C = -100\text{mA}$
Turn-Off Time	T_{off}	–	–	650	ns	$I_{B1} = I_{B2} = -5\text{mA}$

 Note: 11. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.

Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

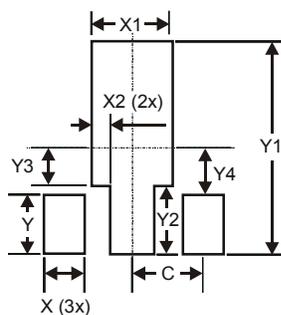


Package Outline Dimensions



SOT89		
Dim	Min	Max
A	1.40	1.60
B	0.44	0.62
B1	0.35	0.54
C	0.35	0.44
D	4.40	4.60
D1	1.62	1.83
E	2.29	2.60
e	1.50 Typ	
H	3.94	4.25
H1	2.63	2.93
L	0.89	1.20
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
X	0.900
X1	1.733
X2	0.416
Y	1.300
Y1	4.600
Y2	1.475
Y3	0.950
Y4	1.125
C	1.500